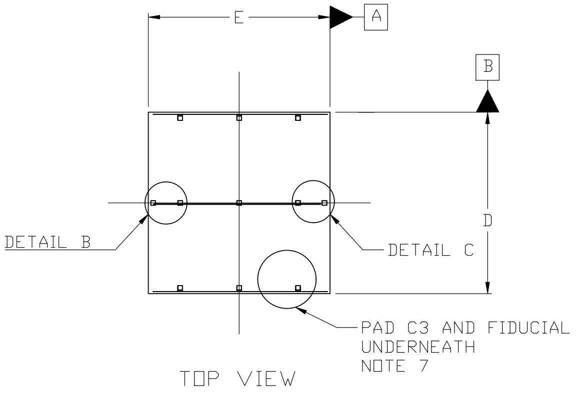
ODCSP8 3.16x3.16x0.64
CASE 570CS
ISSUE A

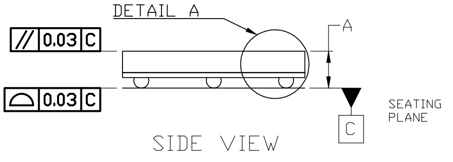
DATE 07 MAY 2019



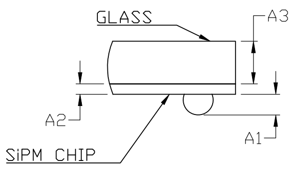
TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. ORIENTATION FIDUCIAL LOCATION. LOCATED BETWEEN PADS C2 AND C3.
7. REFERENCE ONLY, NO ACTUAL ORIENTATION FEATURE ON TOP. SEE DETAIL B AND C AT 10X MAGNIFICATION.

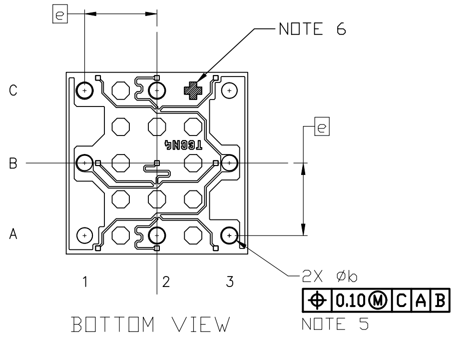


SIDE VIEW

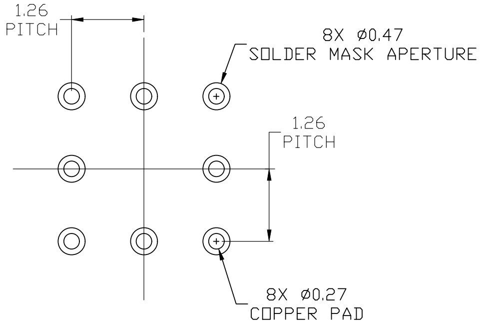


DETAIL A

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.59	0.64	0.69
A1	0.15	0.18	0.20
A2	0.075	0.090	0.105
A3	0.355	0.370	0.385
b	0.23	0.26	0.29
D	3.11	3.16	3.21
E	3.11	3.16	3.21
e	1.26 BSC		



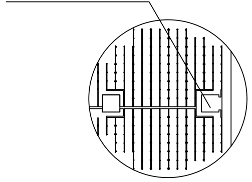
BOTTOM VIEW



RECOMMENDED
MOUNTING FOOTPRINT*
NSMD TYPE

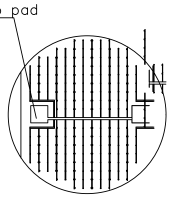
* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Horizontal metal track on silicon not connected to pad



DETAIL C
ORIENTATION DETAIL VIEW

Horizontal metal track on silicon connected to pad

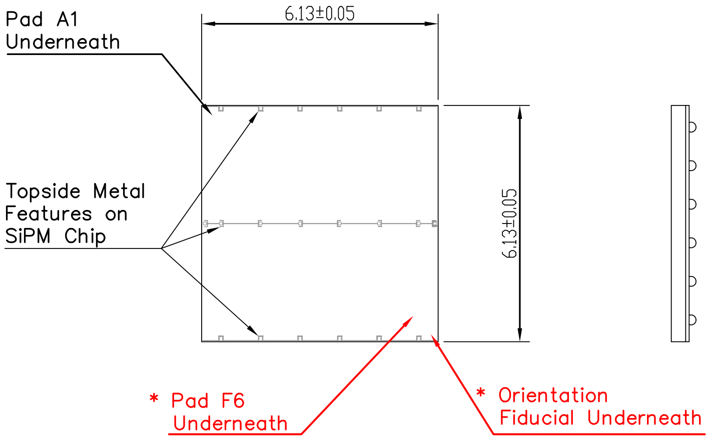


DETAIL B
ORIENTATION DETAIL VIEW

DOCUMENT NUMBER:	**98AON93900G**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	**ODCSP8 3.16x3.16x0.64**	**PAGE 1 OF 1**

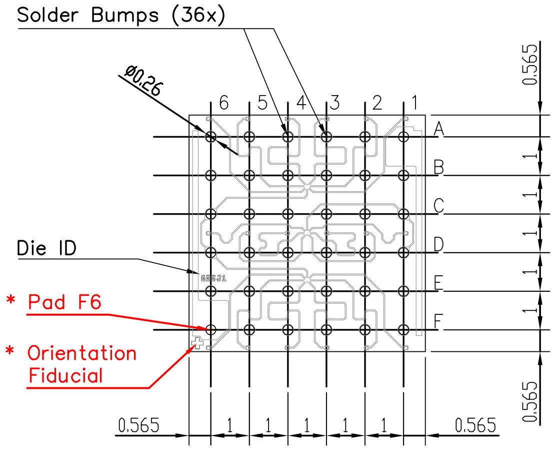
ODCSP36 6x6, 1.0P
CASE 570CP
ISSUE A

DATE 12 FEB 2019



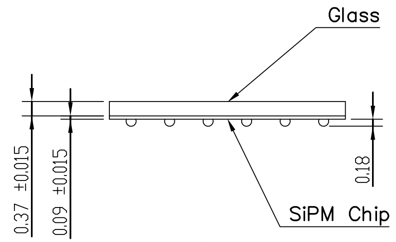
Top View

Side View

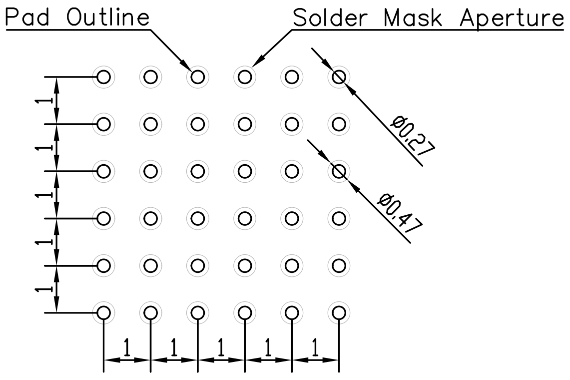


Bottom View

* NOTE Orientation fiducial indicates location of Pad F6



Side View



Recommended PCB Solder Footprint

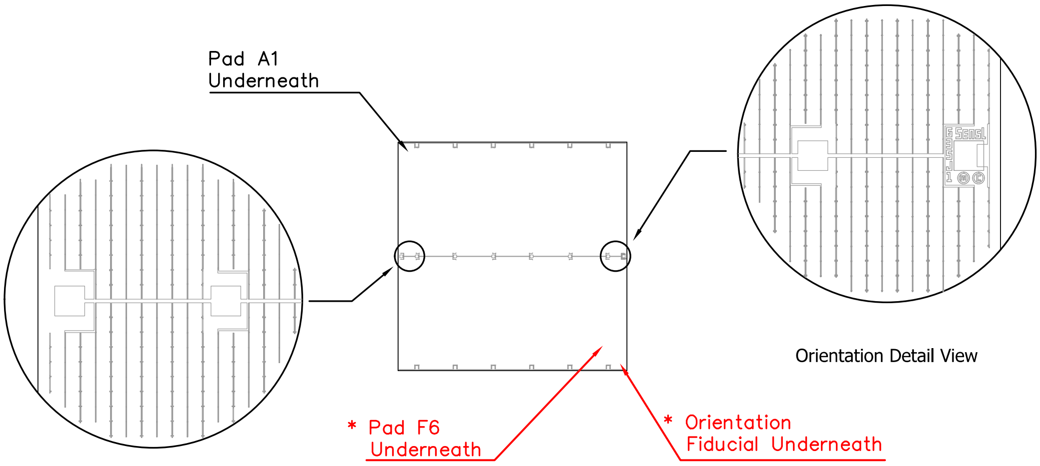
NOTE: The No Connect (NC) pins are electrically isolated and should be soldered to a ground (or bias) plane to help with heat dissipation.

DOCUMENT NUMBER:	**98AON94888G**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**ODCSP36 6x6, 1.0P**	**PAGE 1 OF 2**

ODCSP36 6x6, 1.0P
CASE 570CP
ISSUE A

DATE 12 FEB 2019

Pad Assignments	
Pad#	Function
A1	Cathode
A2	NC
A3	NC
A4	NC
A5	NC
A6	NC
B1	NC
B2	NC
B3	NC
B4	NC
B5	NC
B6	NC
C1	Anode
C2	NC
C3	NC
C4	NC
C5	NC
C6	Fast Output
D1	Anode
D2	NC
D3	NC
D4	NC
D5	NC
D6	Fast Output
E1	NC
E2	NC
E3	NC
E4	NC
E5	NC
E6	NC
F1	NC
F2	NC
F3	NC
F4	NC
F5	NC
F6	Cathode



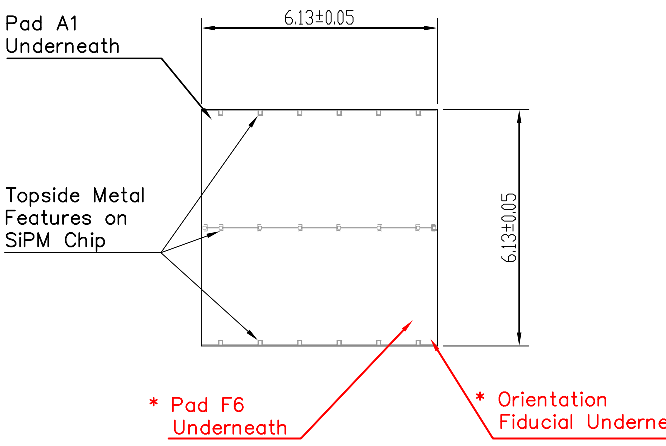
Orientation Detail View

Top View

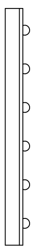
* NOTE Orientation fiducial indicates location of Pad F6

ODCSP36 6x6, 1.0P
CASE 570CP
ISSUE A

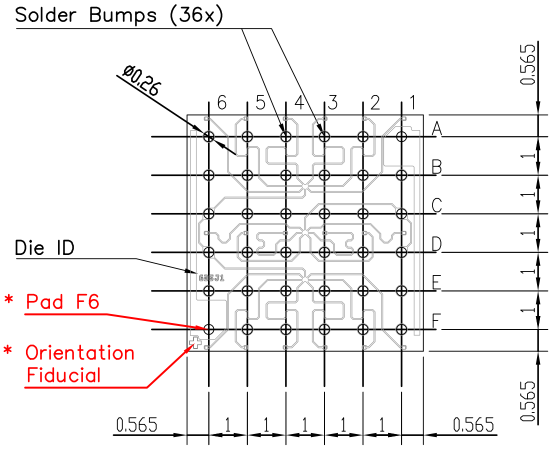
DATE 12 FEB 2019



Top View

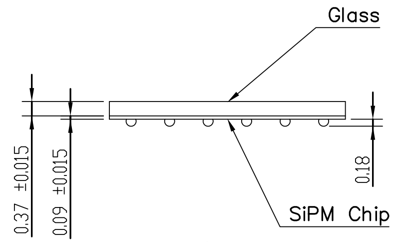


Side View

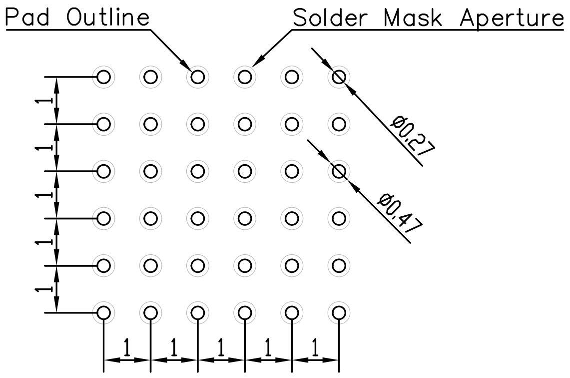


Bottom View

* NOTE Orientation fiducial indicates location of Pad F6



Side View



Recommended PCB Solder Footprint

NOTE: The No Connect (NC) pins are electrically isolated and should be soldered to a ground (or bias) plane to help with heat dissipation.

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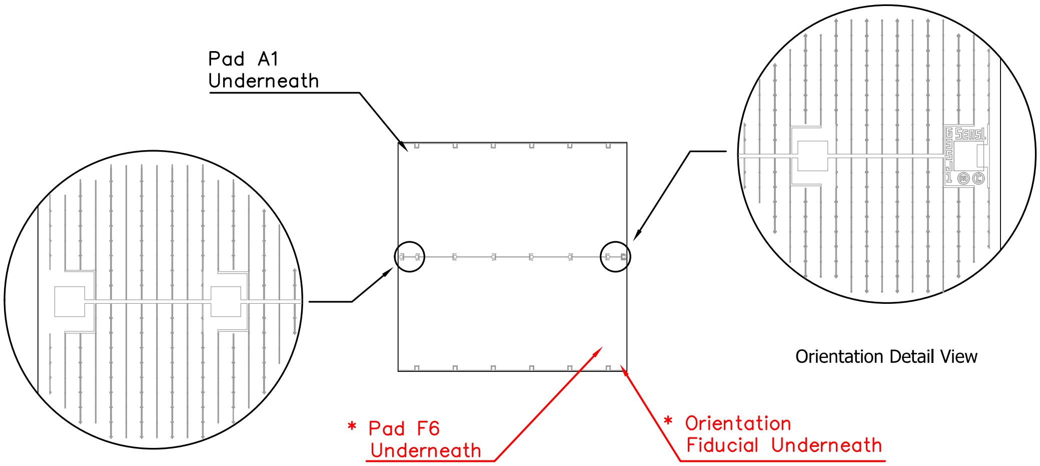
DESCRIPTION:	**ODCSP36 6x6, 1.0P**	**PAGE 1 OF 2**

ODCSP36 6x6, 1.0P
CASE 570CP
ISSUE A

DATE 12 FEB 2019

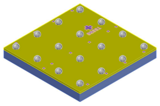
Pad Assignments	
Pad#	Function
A1	Cathode
A2	NC
A3	NC
A4	NC
A5	NC
A6	NC
B1	NC
B2	NC
B3	NC
B4	NC
B5	NC
B6	NC
C1	Anode
C2	NC
C3	NC
C4	NC
C5	NC
C6	Fast Output
D1	Anode
D2	NC
D3	NC
D4	NC
D5	NC
D6	Fast Output
E1	NC
E2	NC
E3	NC
E4	NC
E5	NC
E6	NC
F1	NC
F2	NC
F3	NC
F4	NC
F5	NC
F6	Cathode



Orientation Detail View

Top View

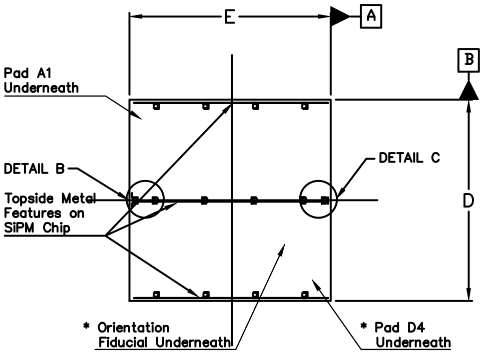
* NOTE Orientation fiducial indicates location of Pad F6



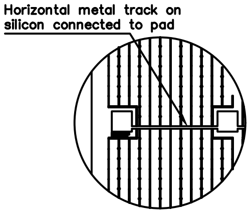
ODCSP16 4x4, 1.12P

CASE 570CN
ISSUE A

DATE 07 JAN 2021



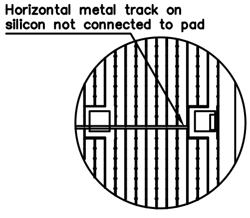
TOP VIEW



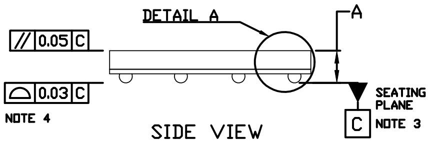
DETAIL B

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. SOLDER BALLS ARE PERFECTLY ALIGNED TO THE CENTER OF THE SENSOR (ACTIVE AREA).

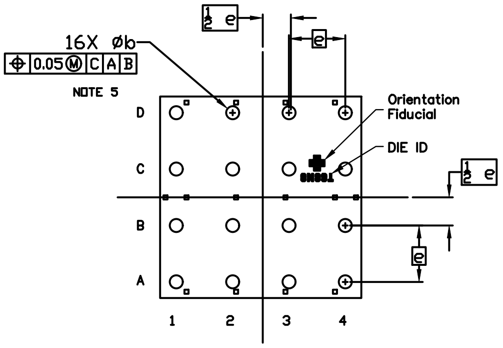
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.60	0.64	0.68
A1	0.16	0.18	0.20
A2	0.075	0.09	0.105
A3	0.355	0.37	0.385
b	0.23	0.26	0.29
D	3.95	4.00	4.05
E	3.95	4.00	4.05
e	1.12 BSC		



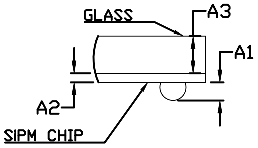
DETAIL C



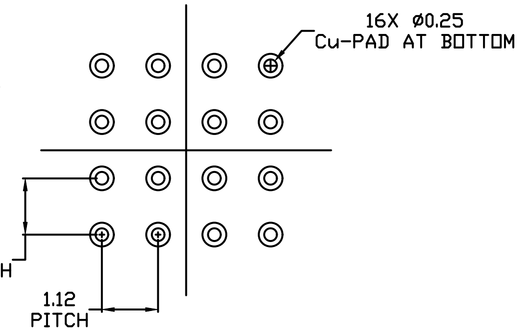
SIDE VIEW



BOTTOM VIEW



DETAIL A



RECOMMENDED
MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

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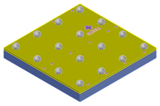
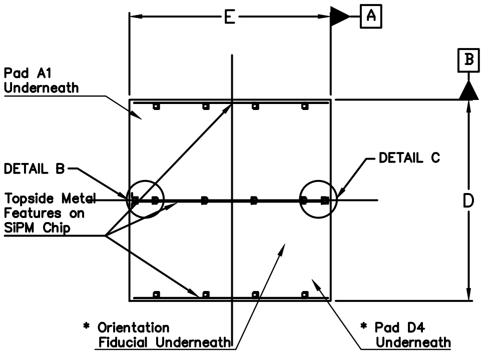
DOCUMENT NUMBER:	**98AON94887G**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	**ODCSP16 4x4, 1.12P**	**PAGE 1 OF 1**

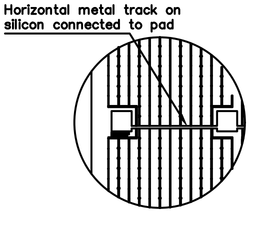


ODCSP16 4x4, 1.12P
CASE 570CN
ISSUE A

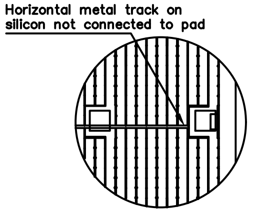
DATE 07 JAN 2021



TOP VIEW



DETAIL B



DETAIL C

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
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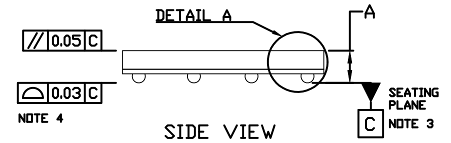
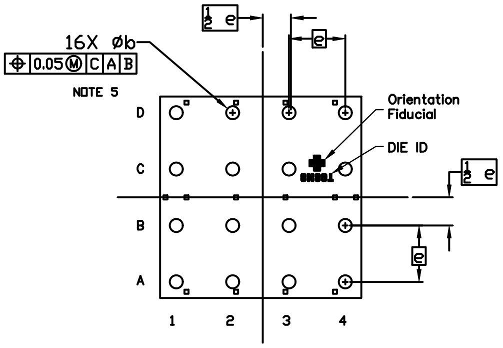
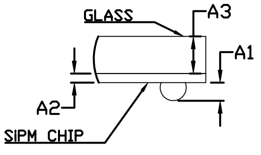
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.60	0.64	0.68
A1	0.16	0.18	0.20
A2	0.075	0.09	0.105
A3	0.355	0.37	0.385
b	0.23	0.26	0.29
D	3.95	4.00	4.05
E	3.95	4.00	4.05
e	1.12 BSC		



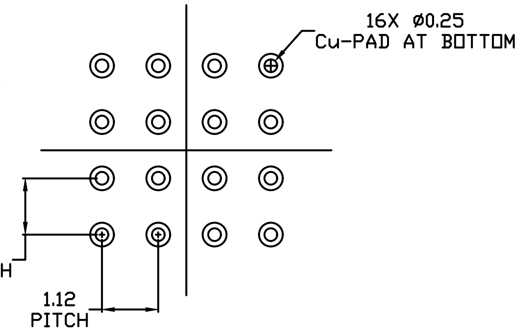
SIDE VIEW



BOTTOM VIEW



DETAIL A



RECOMMENDED
MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

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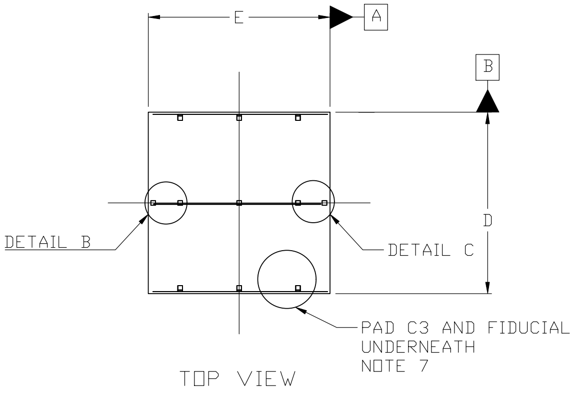
DESCRIPTION:	**ODCSP16 4x4, 1.12P**	**PAGE 1 OF 1**

ODCSP8 3.16x3.16x0.64
CASE 570CS
ISSUE A

DATE 07 MAY 2019



TOP VIEW

NOTES:

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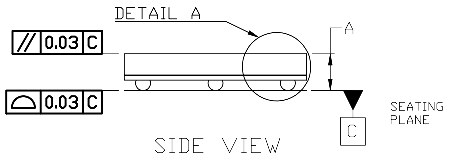
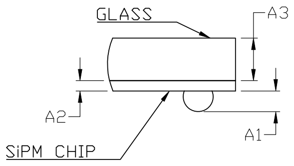
7. REFERENCE ONLY, NO ACTUAL ORIENTATION FEATURE ON TOP. SEE DETAIL B AND C AT 10X MAGNIFICATION.



SIDE VIEW



DETAIL A

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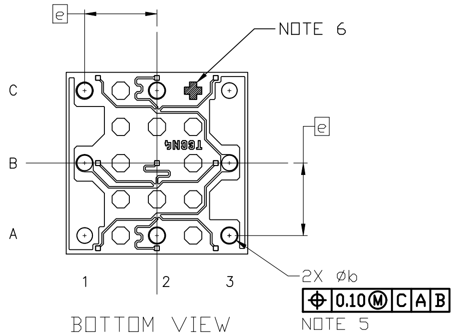
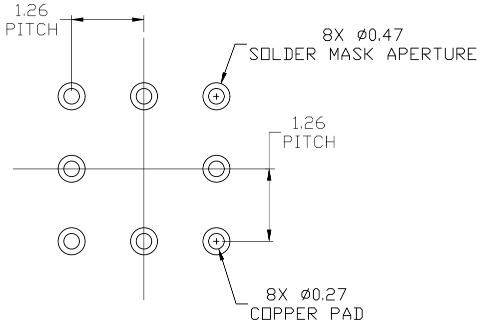


BOTTOM VIEW



RECOMMENDED
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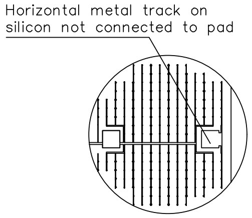
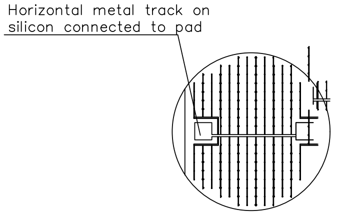


DETAIL C
ORIENTATION DETAIL VIEW



DETAIL B
ORIENTATION DETAIL VIEW

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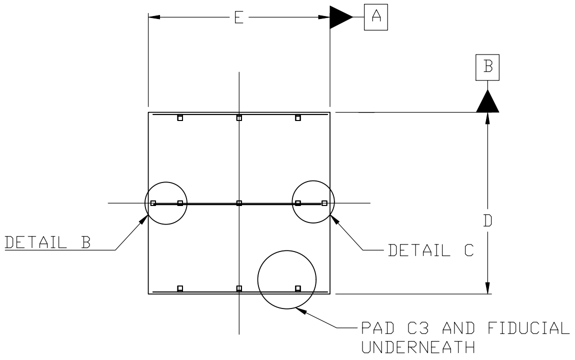
DESCRIPTION:	**ODCSP8 3.16x3.16x0.64**	**PAGE 1 OF 1**

ODCSP8 3.16x3.16x0.64

CASE 570CS
ISSUE A

DATE 07 MAY 2019



TOP VIEW

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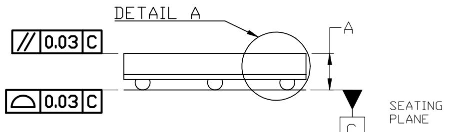
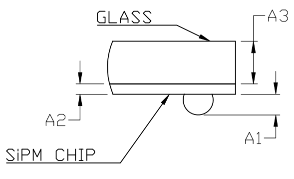


SIDE VIEW



DETAIL A

DIM	MILLIMETERS		
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A	0.59	0.64	0.69
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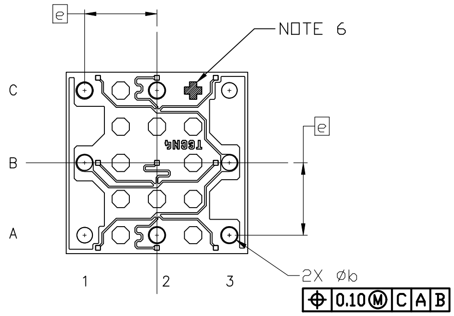
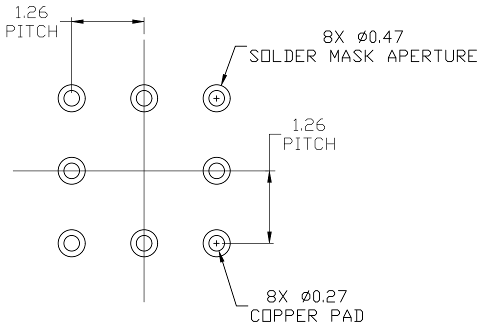
A3	0.355	0.370	0.385
b	0.23	0.26	0.29
D	3.11	3.16	3.21
E	3.11	3.16	3.21
e	1.26 BSC		

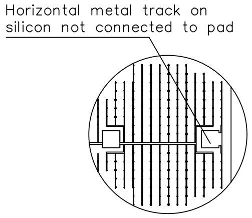


BOTTOM VIEW

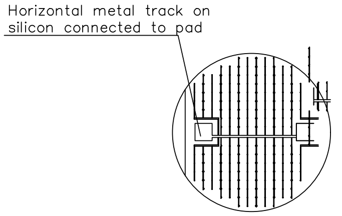


RECOMMENDED
MOUNTING FOOTPRINT*
NSMD TYPE

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



DETAIL C
ORIENTATION DETAIL VIEW



DETAIL B
ORIENTATION DETAIL VIEW

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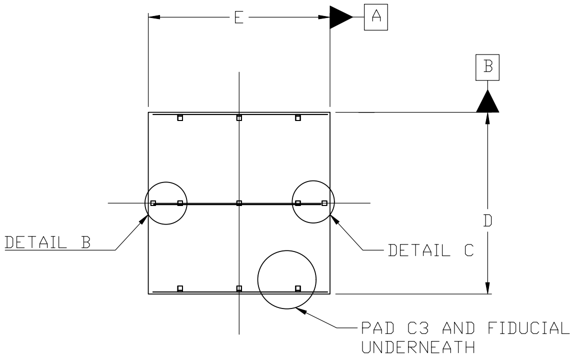
ODCSP8 3.16x3.16x0.64
CASE 570CS
ISSUE A

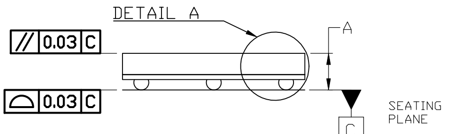
DATE 07 MAY 2019



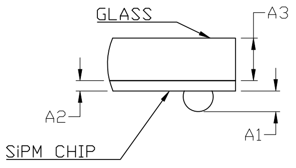
TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. ORIENTATION FIDUCIAL LOCATION. LOCATED BETWEEN PADS C2 AND C3.
7. REFERENCE ONLY, NO ACTUAL ORIENTATION FEATURE ON TOP. SEE DETAIL B AND C AT 10X MAGNIFICATION.

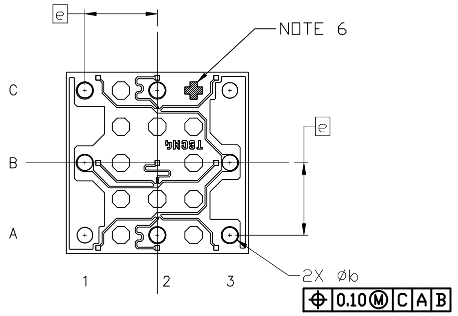


SIDE VIEW

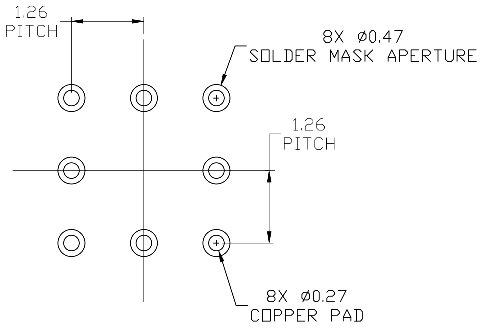


DETAIL A

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.59	0.64	0.69
A1	0.15	0.18	0.20
A2	0.075	0.090	0.105
A3	0.355	0.370	0.385
b	0.23	0.26	0.29
D	3.11	3.16	3.21
E	3.11	3.16	3.21
e	1.26 BSC		



BOTTOM VIEW



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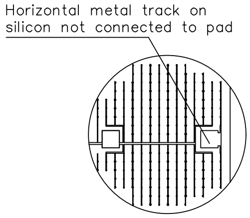
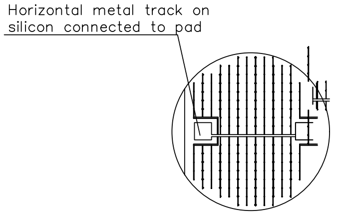


DETAIL C
ORIENTATION DETAIL VIEW



DETAIL B
ORIENTATION DETAIL VIEW

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